

Highly density GPU server  
based on Intel Xeon Scalable 3rd generation



No contractual

Isometric view



No contractual

Front view

## Key Features



19-inch - 1U/4 GPUs



Dual Intel® Xeon®  
3<sup>rd</sup> Gen socket



32x DDR4 @ 3200MHz



4x PCIe 4.0 x16 for GPU/FPGAs  
2x PCIe 4.0 x16 LP  
1x OCP 3.0 x16



Air Cooling

### 3rd Gen Intel® Xeon® Scalable Processors

The Godí 1.4iP is built with the latest Intel® Xeon® Scalable Processors, and designed for the demand of high scalability, high density computing, and widest range of workloads. 3rd Gen Intel® Xeon® Scalable processors offer a balanced architecture with built-in acceleration and advanced security capabilities.

### Cloud and Enterprise Made Flexible

The latest 3rd Gen Intel® Xeon® Scalable processors are built upon years of cloud innovation, tuned to your unique needs with built-in AI and Intel® Crypto Acceleration and advanced security capabilities.

### The acceleration at its best with NVIDIA & AMD GPUs or FPGAs

From 3D modeling, CAD and amazing visualisation renders, to the most demanding AI training and Inference workloads, the Godí 1.4iP enables any of NVIDIA's latest Tesla, Quadro and AMD Mi GPU series to be used at its best performances.

Need to decode many audio and video feeds ? The Godí 1.4iP can also carry multiple FPGAs, allowing a single system to run an entire infrastructure.

### The acceleration at its best with NVIDIA & AMD GPUs or FPGAs

With all acceleration cards in front IO, in addition to better cooling capabilities, the IO is now accessible in the front.

From High density network to direct access to FPGAs or video outputs, the Godí 1.4iP is the only server on the market designed to be deployed as much on single entity mode as in data center environment.



**SCAN THE CODE!**

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## SPECIFICATIONS

<b>System</b>	<b>Model</b>	BRB-GI1-104iP-R010
	<b>Form factor</b>	1U
	<b>Nodes</b>	1
	<b>Dimension</b>	482mm (W) x 900mm (D) x 44mm (H) 19" (W) x 35,43" (D) x 1.73" (H)
	<b>Cooling Technology</b>	Air Cooling
<b>Storage</b>	<b>Internal type</b>	1x M.2 NVMe PCIe3.0 x4 support 2280/2260/2242
	<b>External type</b>	None
	<b>RAID Controller</b>	None
<b>Motherboard</b>	<b>CPU</b>	2x Socket P+ (LGA 4189) Intel® XEON® 3rd Generation Scalable Processors family TDP 270W maximum/CPU
	<b>Chipset</b>	Intel C621A
	<b>Expansion slots</b>	4x PCIe4.0 x16 slots for FHFL GPU/FPGA form factor TDP up to 250W/Card 2x PCIe4.0 x16 slot 1x OCP 3.0 PCIe4.0 x16 slot
	<b>BMC</b>	Integrated Aspeed® AST2500
	<b>TPM</b>	1x (13-pin,SPI)
<b>Memory</b>	<b>Total slots</b>	32 (8-channel per CPU)
	<b>Capacity</b>	Maximum up to 4TB per Node ( (Using RDIMM 3DS 128GB)
	<b>Memory type</b>	DDR4 2933/3200 RDIMM up to 128GB DDR4 2933/3200 LR-DIMM 3DS up to 128GB
<b>Network</b>		1x 1GbE Management Port dedicated to the IPMI
<b>I/O</b>	<b>Rear</b>	1x VGA Port (DB15) 1x Dedicated IPMI 1x DB9 2x USB 3.2 1x UID 1x PWR BTN
<b>Management Solution</b>	<b>Software</b>	AMI MegaRAC
	<b>Out of band remote management</b>	WebGUI, Intelligent Platform Management Interface (IPMI)
<b>Power Supply</b>	<b>Type</b>	1+1 Redundant CRPS
	<b>Power rating</b>	1600W 180–240Vac
	<b>Power Efficiency</b>	80 PLUS Platinum (94%)
<b>Operating Environment</b>	<b>Operating Temperature</b>	Operation temperature: 10°C ~ 35°C (50°F ~ 95°F)
	<b>Non-operating Temperature</b>	Non operation temperature: -40°C ~ 60°C (40° ~ 140°F)
	<b>Operating Relative Humidity</b>	Up to 90%
	<b>Non-operating Relative Humidity:</b>	95%, non-condensing at 35° C
<b>Warranty</b>	2CRSi hardware warranty includes a one year, parts and labour with return to 2CRSi selling entity. Customers may purchase an extended warranty of up to 3 years on parts and labour with different support levels. Please contact 2CRSi at <a href="mailto:support@2crsi.com">support@2crsi.com</a> or reach your sales point of contact for complete warranty details including limitations and transferability. <a href="https://2crsi.com/global-location">2crsi.com/global-location</a>	